## nexperia

## **Reliability Monitoring Results**

## Quarters: Q1/2021 to Q4/2021

Based on structural similarity

Suppli	ier	User Part Number							
Nexperi	ia B.V.	74AHCT1G00GW-Q100	74AHCT1G00GW-Q100						
Part D	Description: Single 2-input I	NAND gate; TTL enabled							
Pro	nction Family: AHC(T) ocess family: Super micron ckage family: TSSOP								
JESD4	17 Test	Test Conditions	Duration	# Lots	# Quantity	# Rejects			
# 1	TEST Pre- and Post-Stress Electrical Test	Tamb = 25 °C	N/A	see below	all parts	see below			
# 2	<b>PC</b> Preconditioning	JESD22-A113 MSL 1	N/A	863	73980	0			
# 5a	HTOL EFR High Temperature Operating Life Extrinsic	JESD22-A108 Tj = 150°C V <sub>CCMAX</sub> $\leq$ V $\leq$ 1.2*V <sub>CCMAX</sub>	48 hours or 168 hours	128	38474	0			
# 5b	HTOL IFR High Temperature Operating Life Intrinsic	JESD22-A108 Tj = 150°C $V_{CCMAX} \le V \le 1.2^*V_{CCMAX}$	≥500 hours	76	5079	0			
# 7	TC Temperature Cycling	JESD22-A104 -65 °C to 150°C	≥500 cycles	478	37734	0			
# 9	uHAST / HAST unbiased or biased High Accelerated Stress Test	JESD22-A101 Tamb = 130 °C, RH = 85%, V = V <sub>CCMAX</sub>	96 hours	462	36246	0			

## **Calculation of PPM, FIT and MTTF**

Test considered for PPM calculation: High Temperature Operating LifeTest Extrinsic (HTOL EFR, Test # 5a above) Test considered for FIT and MTTF calculations: High Temperature Operating LifeTest Intrinsic(HTOL IFR, Test # 5b above)

Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

Product Family	Package Family	Quantity	Rejects	Extrinsic Failure Rate (PPM)	Intrinsic Failure Rate (FIT)	MTTF (hrs)
AHC(T)	TSSOP	5079	0	24	0.7	1.57 E+09

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